

DC Copper Plating for Thick Panel

厚板高纵横比 电镀铜技术

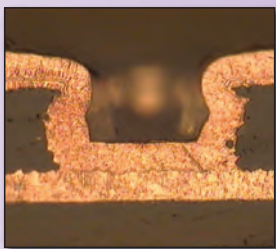
Next Generation of Thick Panel Copper Plating Technology

A latest technology is under developed for thick panel plating, which provides better throwing power under a basis of 10~20% higher current density than existing product. Obviously, it helps to increase plating efficiency and obtainable higher productivity without any required equipment investment.

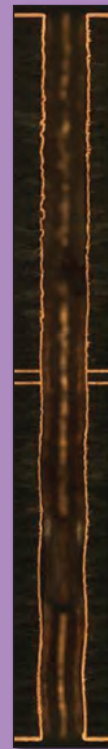
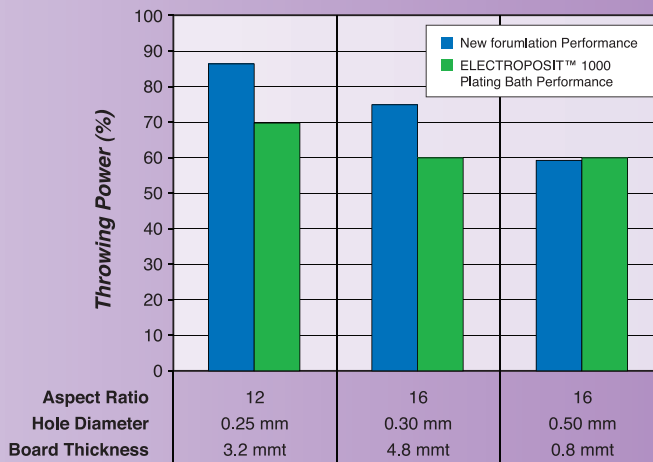
陶氏电子材料，最新一代的厚板电镀技术正在开发中。在相对于现有产品高于10~20%电流密度的基础上，它将能提供较佳的通孔贯孔能力。显而易见的，它有助提高电镀效率与产能且不需任何设备的额外投资。

Advantage of New Process 新制程具备以下优越的特性

- High throwing power
高通孔贯孔能力
 - at higher plating current density
于较高电流密度下
 - on high aspect ratio boards
于高纵横度板
 - on microvia
于微盲孔电镀
- Microvia plating capability
可同时兼顾微盲孔电镀
- Full analysis system by CVS
可使用 CVS分析所有添加剂
- Excellent thermal reliability
优越的热信赖



Via diameter: 6 mil
Via deep: 4 mil
Aspect Ratio: 0.67:1
CD: 12 ASF



Hole diameter: 0.5 mm
Panel thickness: 8 mm
Aspect Ratio: 16:1
CD: 12 ASF

